IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	© Copyright 2005. IPC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		der both This docum level parts,	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				ials and M	fg Informati	on		
upplier Infor									,		<u>, </u>			
Company name*			Company unique ID			Unique ID Authority				Response Date*				
nsemi										2024-05-	2024-05-09			
Contact Name			Title - Contact			Phone - Contact*				Email - Contact*				
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
uthorized Repre	sentative*		Title - Representative			Phone - Representative*			Email - Representative*					
Product-Env-Stewards			Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
Reques	ster Item Number	NCP13992ANDR2G High Perf Current		Mfr Item Name		Effective Da	ate Vers	sion	Manufacturing Site	1	Weight*	UOM	Unit Type	
				High Perf Current N with Integrated HV	Mode Resonant Controller Drivers	2024-05-09	09 PH1		1	179.58	mg	Each		
Ianufacturing	g Proccess Information	on												
Terminal Plating / Grid Array Material Terminal Plating / Grid Array Material			erminal Base Alloy J-STD-020 MSL Ratin		STD-020 MSL Rating	Peak Process Body Temperature Max Time at Pea			k Temperature Number of Reflow Cycles					
Matte Tin (Sn) - annealed		C	CU Alloy 3			260	0 C		30	secon	ds 3			
omments														
TTENTION: MS	SL 3 Rated item requires l	Bake and D	ry Pack (after	electrical test)					<u> </u>					
or more informa	tion regarding material co	omposition 1	olease refer to	page 3	_	•	•	•	_	•			_	

RoHS Material Composition Declaration			Declaration Type *	Detail	ed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (100 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of										
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted					
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the					

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	5.37	mg	Supplier	Silicon (Si)	7440-21-3		5.37	mg
Die Attach	0.58	mg	Supplier	Organic peroxide	3006-86-8		0.0043	mg
			Supplier	Diluent B	Proprietary Data		0.029	mg
			Supplier	Diluent A	Proprietary Data		0.0232	mg
			Supplier	Dicyandiamine	461-58-5		0.0014	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.464	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.058	mg
Lead Frame	70.13	mg	Supplier	Silver (Ag)	7440-22-4		0.561	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0842	mg
			Supplier	Iron (Fe)	7439-89-6		1.6481	mg
			Supplier	Copper (Cu)	7440-50-8		67.8157	mg
			Supplier	Phosphorus (P)	7723-14-0		0.021	mg
Mold Compound-Black	101.52	mg		Epoxy resin	proprietary data		5.076	mg
			Supplier	Phenolic Resin	Proprietary Data		2.0304	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		2.538	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5076	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		91.368	mg
Plating	1.87	mg	Supplier	Tin (Sn)	7440-31-5		1.87	mg
Wire Bond	0.11	mg	Supplier	Palladium (Pd)	7440-05-3		0.0023	mg
			Supplier	Gold (Au)	7440-57-5		0.0003	mg
			Supplier	Copper (Cu)	7440-50-8		0.1074	mg